TOSHIBA

Report No. SG013299

Heat-resistant Mounting Conditions

Product Name: T6VM8XBG-0001(O)
Package Name: P-BGA419

1.Adaptation table

Reflow	Flow	Soldering iron
3 times maximum	N/A	N/A

a.Reflow

Peak temperature : 260 deg.C maximum instantaneously
Reflow zone : 255 deg.C within 30 seconds, 217 deg.C 60 to 150 seconds
Preheat : 150 to 200 deg.C , 60 to 120 seconds

NOTE: All temperatures refer to the balls.

The heat-resistant temperature profile is shown in Fig.1.
The temperatures in this profile are the maximum guaranteed temperatures that the device endures.
Select the temperatures for a pre-heat and a heat most suitable for your solder paste type, etc. within the conditions described in Fig.1.

Since this package is a dry bag product, from opening to the final reflow should take place within 168hr at 30deg.C/70%RH.

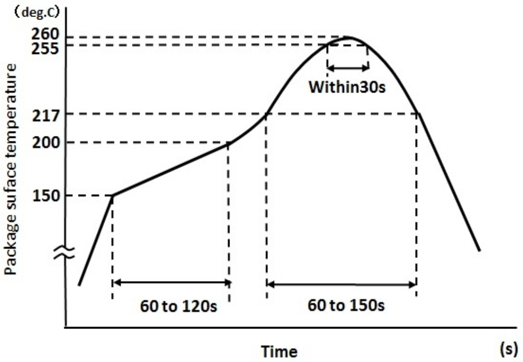

Fig.1 Example of Heat-resistant Temperature Profile

b.Flow

This device is not suitable for flow soldering.

c.Soldering iron

This device is not suitable for hand soldering using a soldering iron.

2.Others

We urge you to verify well before mounting to assure enough solder joint strength.